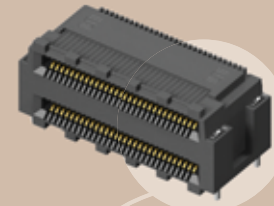


DSEC-50-01-L-07.0-2-RA



DUAL STACK EDGE CARD DSEC SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DSEC

Insulator Material:

Black Liquid Crystal Polymer

Contact:

Copper Alloy

Plating:

Au or Sn over 50µ" (1,27µm) Ni

Current Rating: Testing Now!

Operating Temp: -55°C to +125°C

Card Insertion Depth: (5,94mm) .234" nominal

RoHS Compliant: Yes

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x

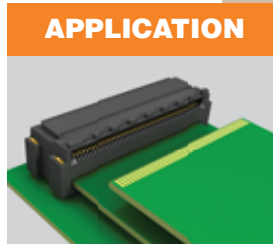
Lead-Free Solderable: Yes

Mates with: 1,60mm (.062") thick cards, HSC8, HSF8

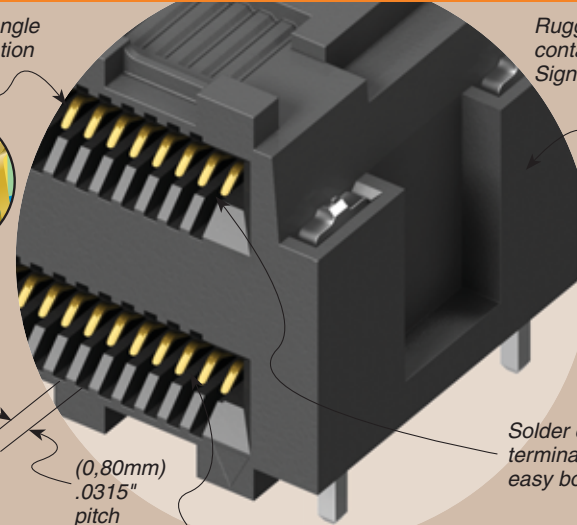


Right Angle Orientation

Rugged Edge Rate™ contacts designed for Signal Integrity



APPLICATION



(0,80mm) .0315" pitch

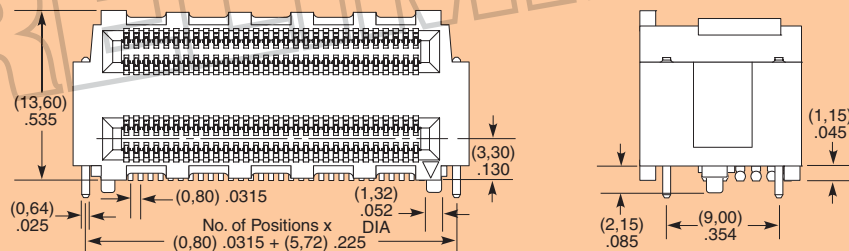
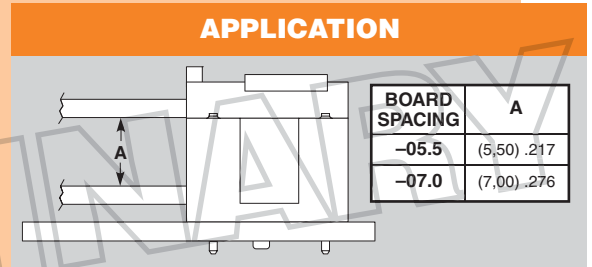
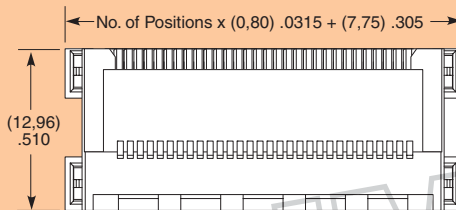
Accepts (1,60mm) .062" PCB thicknesses

Solder charged terminations for easy board processing

ALSO AVAILABLE

- Tin-Lead Solder Charge
 - Other card spacings
 - Single card elevated
- Call Samtec.

DSEC	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	BOARD SPACING	SOLDER TYPE	RA
-30, -40, -50	(Per Row)	-01 = (1,60mm) .062" thick card	-L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail -S = 30µ" (0,76µm) Gold on contact, Matte Tin on tail	-05.5 = (5,5mm) .217" -07.0 = (7mm) .276"	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/ 5% Cu Solder Crimp	



Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM